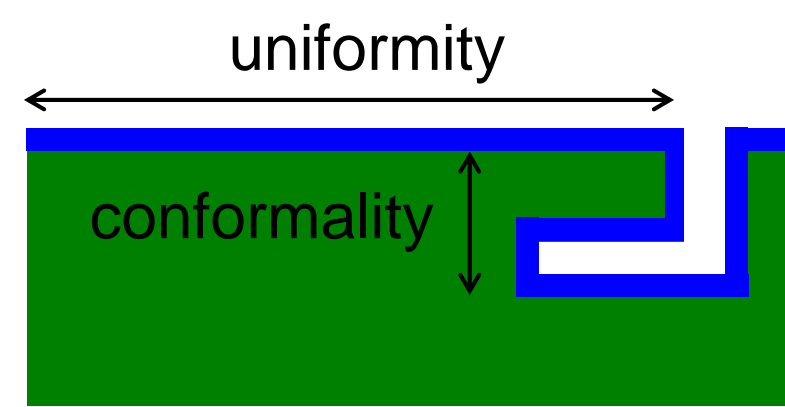


## Introduction

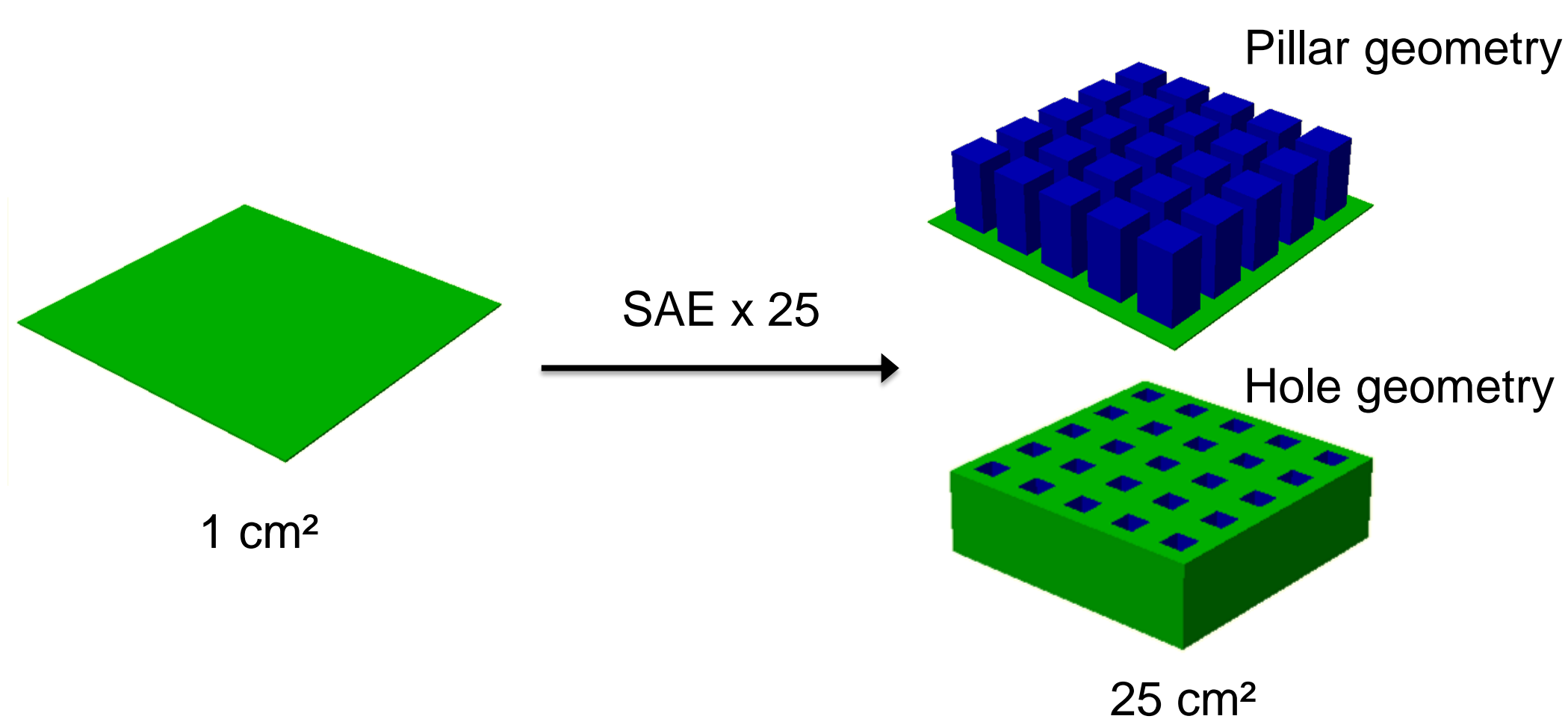
### Atomic Layer Deposition (ALD)

ALD is an ultrathin film deposition method based on sequential self-terminating gas-solid surface reactions. Key advantages of ALD are the atomic level thickness control and excellent conformality.

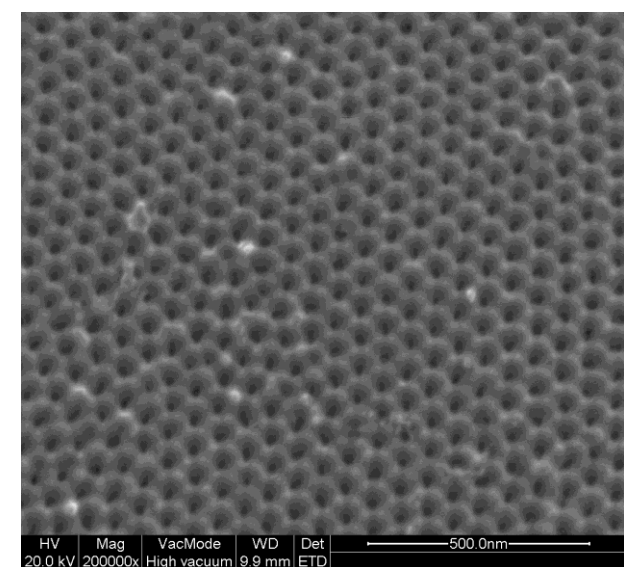


### Surface Area Enhanced (SAE) structures

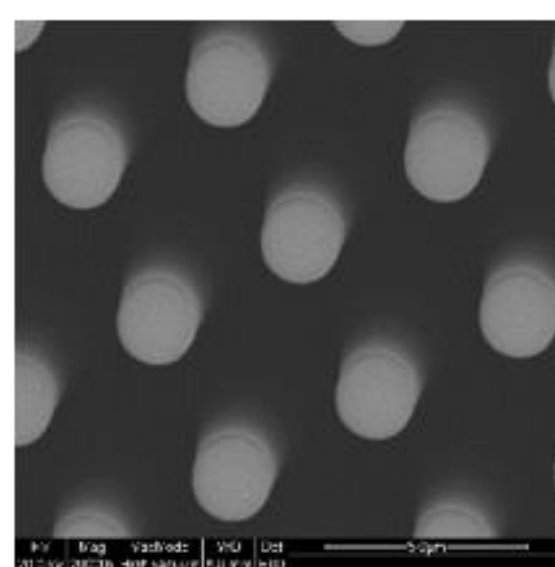
SAE structures are used to increase the active area, for example, in fuel cells, batteries, sensitized solar cells and photocatalytic surfaces.



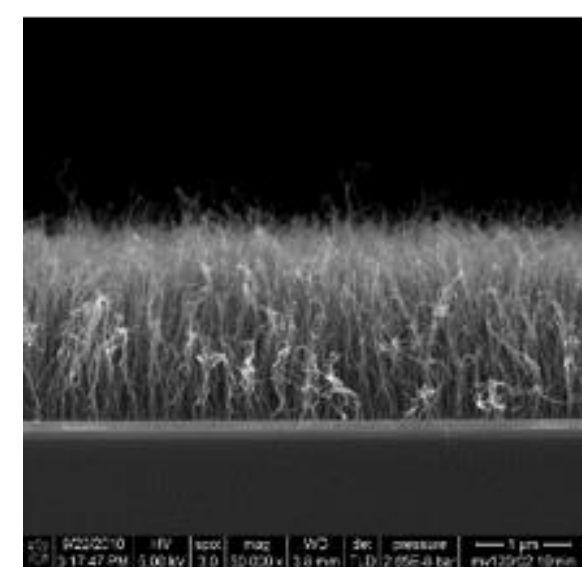
Examples of frequently used SAE structures:



anodic aluminum oxide (AAO) with cylindrical pores



silicon pillars



carbon nanotubes (CNT)

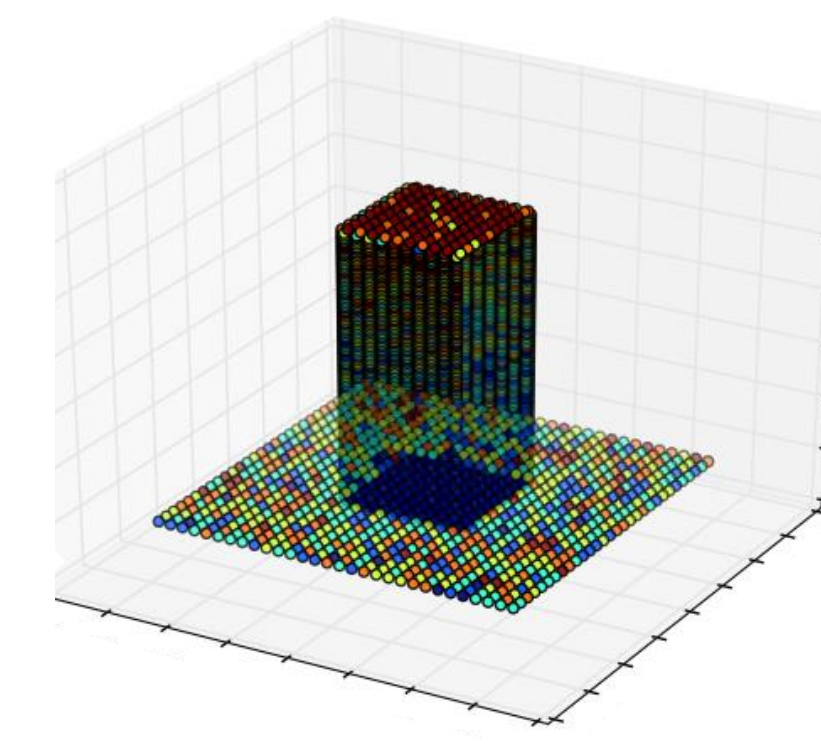
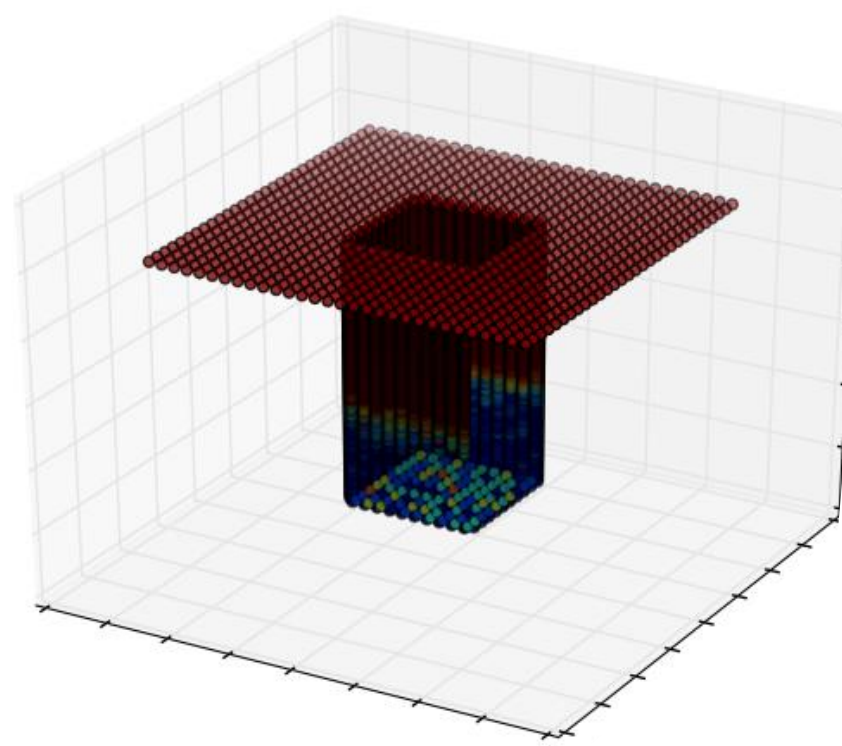
## Simulations

### Model

A 3D Monte Carlo simulation model was developed to optimize the ALD process parameters to achieve conformal coverage of 3D substrates.

$$\text{exposure} = P \cdot t \sim \text{precursor cost}$$

P = partial precursor pressure  
t = precursor pulse time

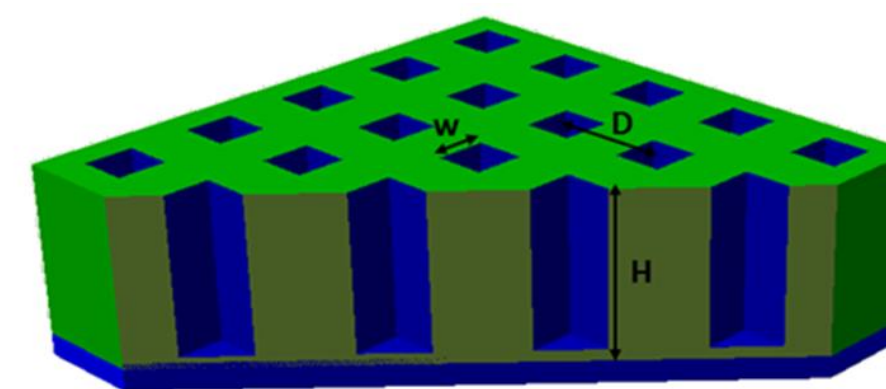


Colour ~ degree of coverage

Blue: uncovered  
Red: completely covered

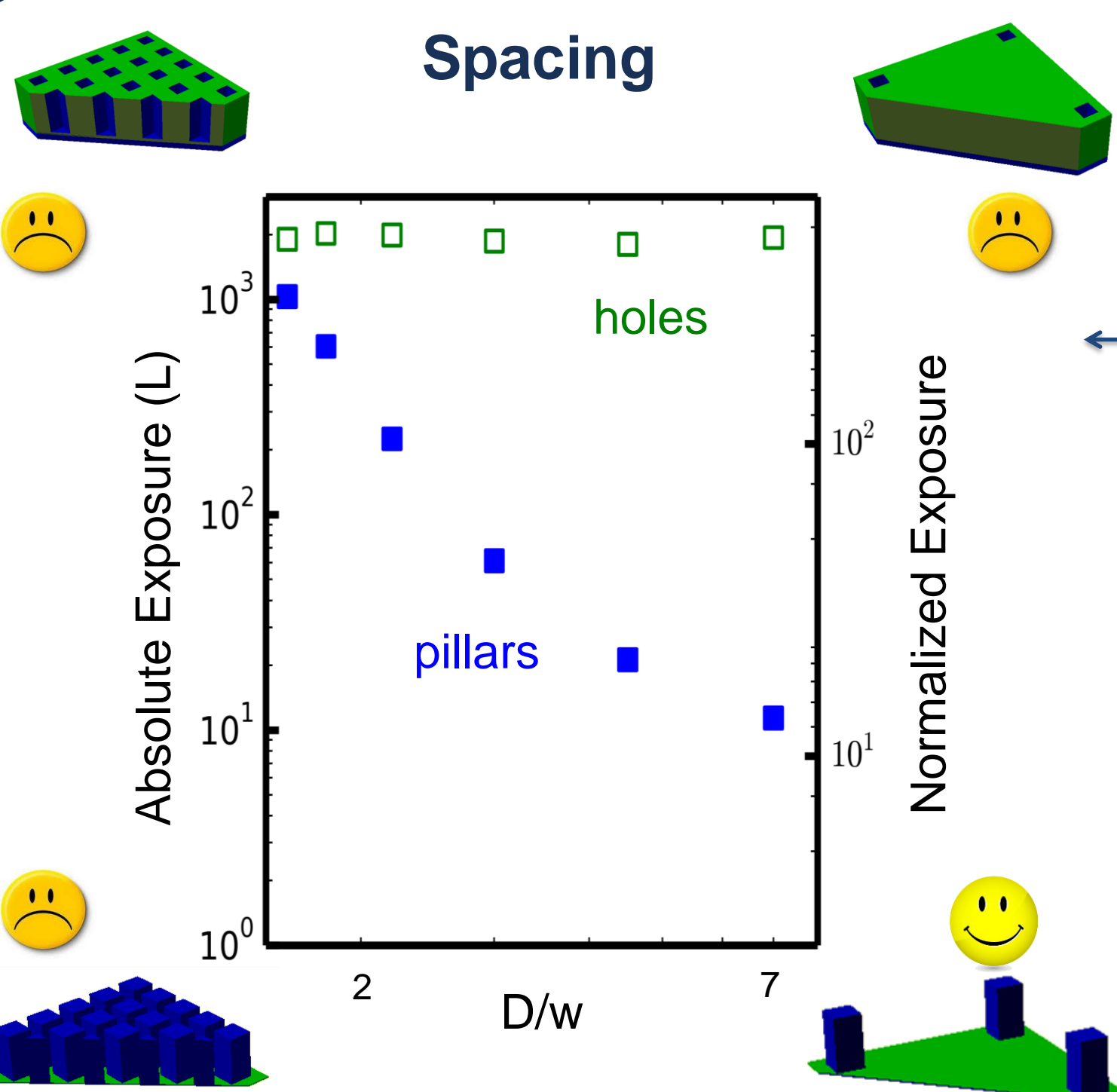
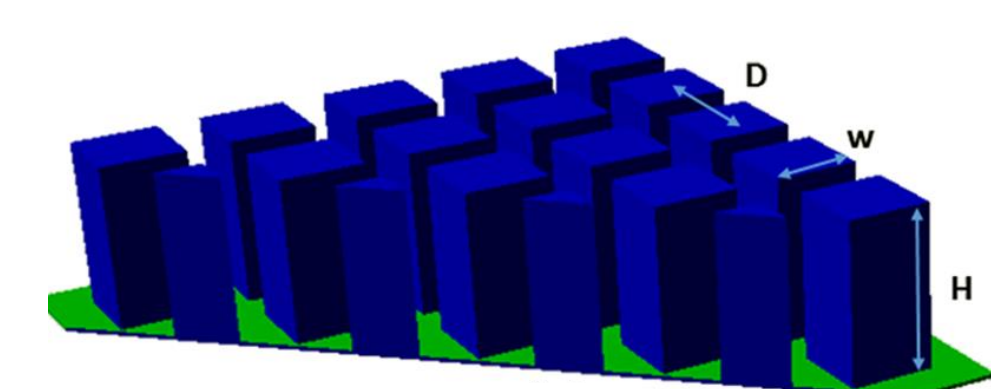
### Objective

To compare the exposure needed to conformally coat an array of pillars or holes with equal surface area. → Which geometry requires the lowest precursor cost?

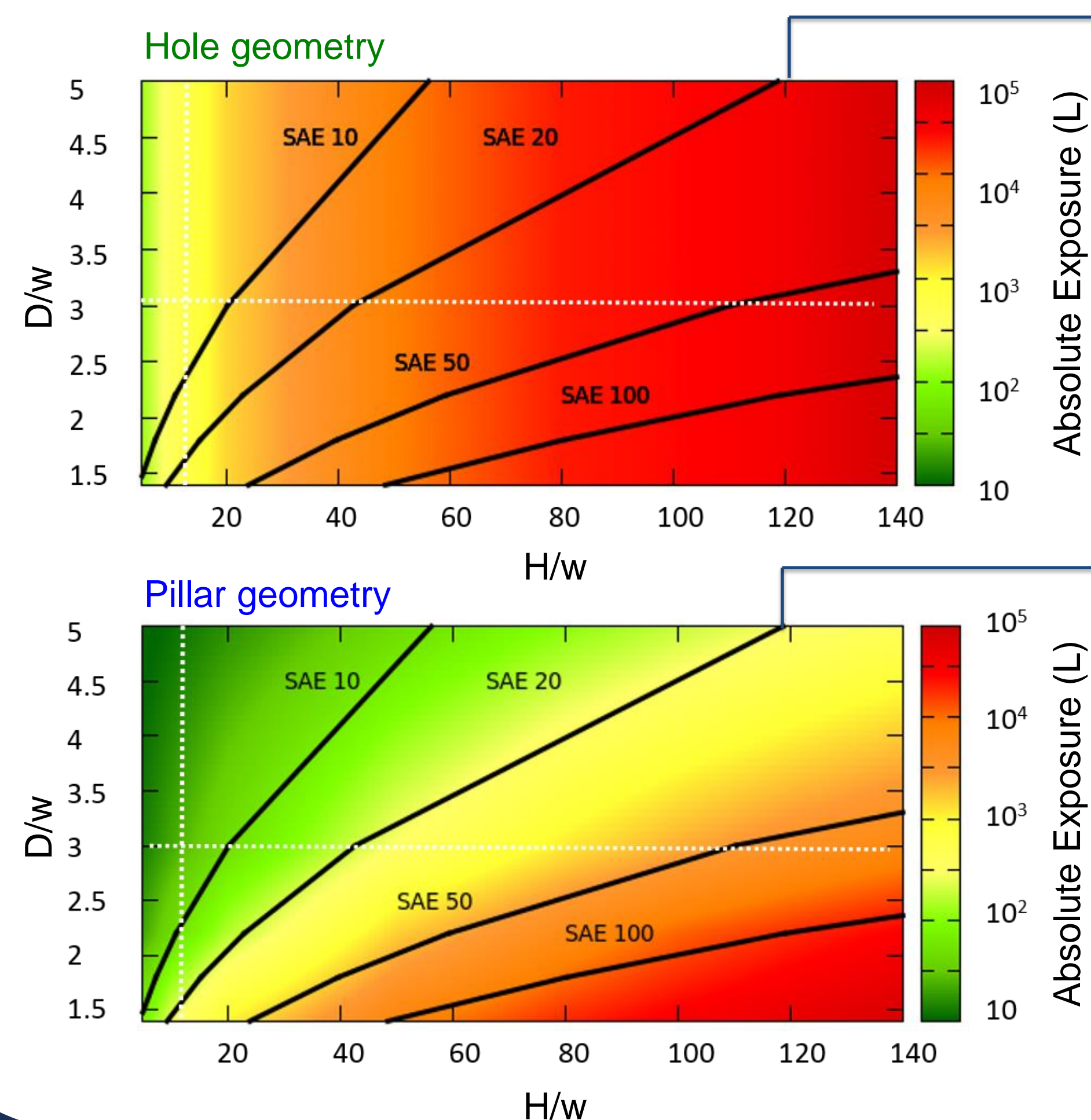
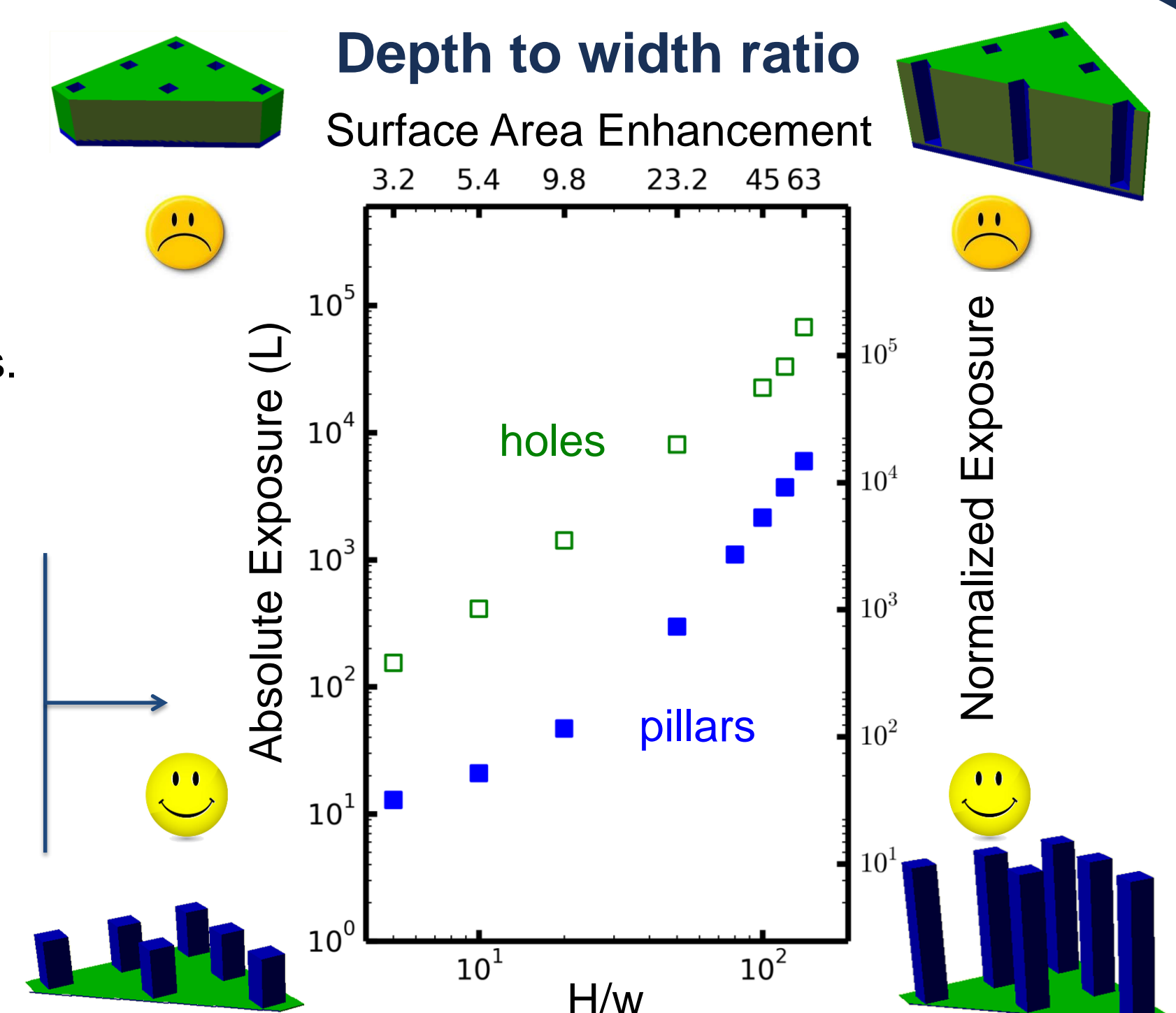


H = height  
w = width

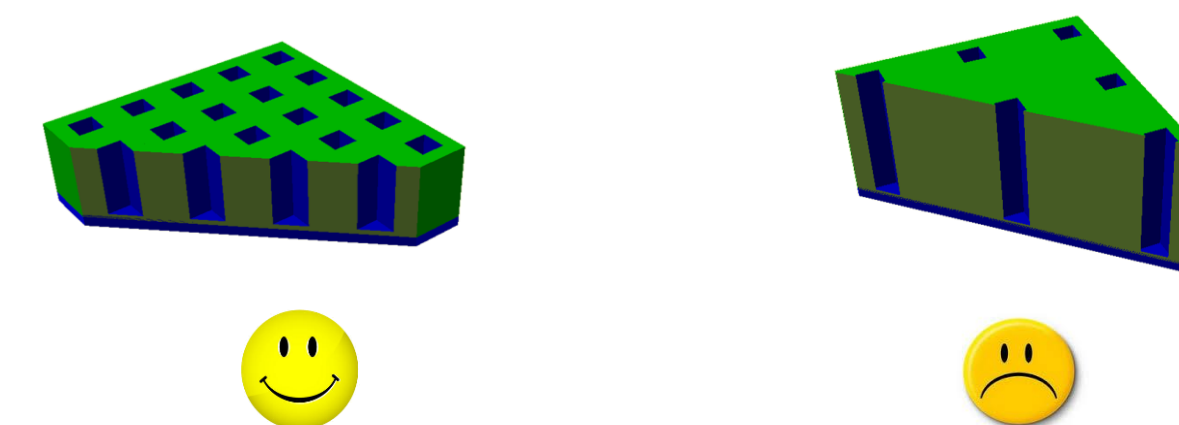
D = center-to-center distance = spacing



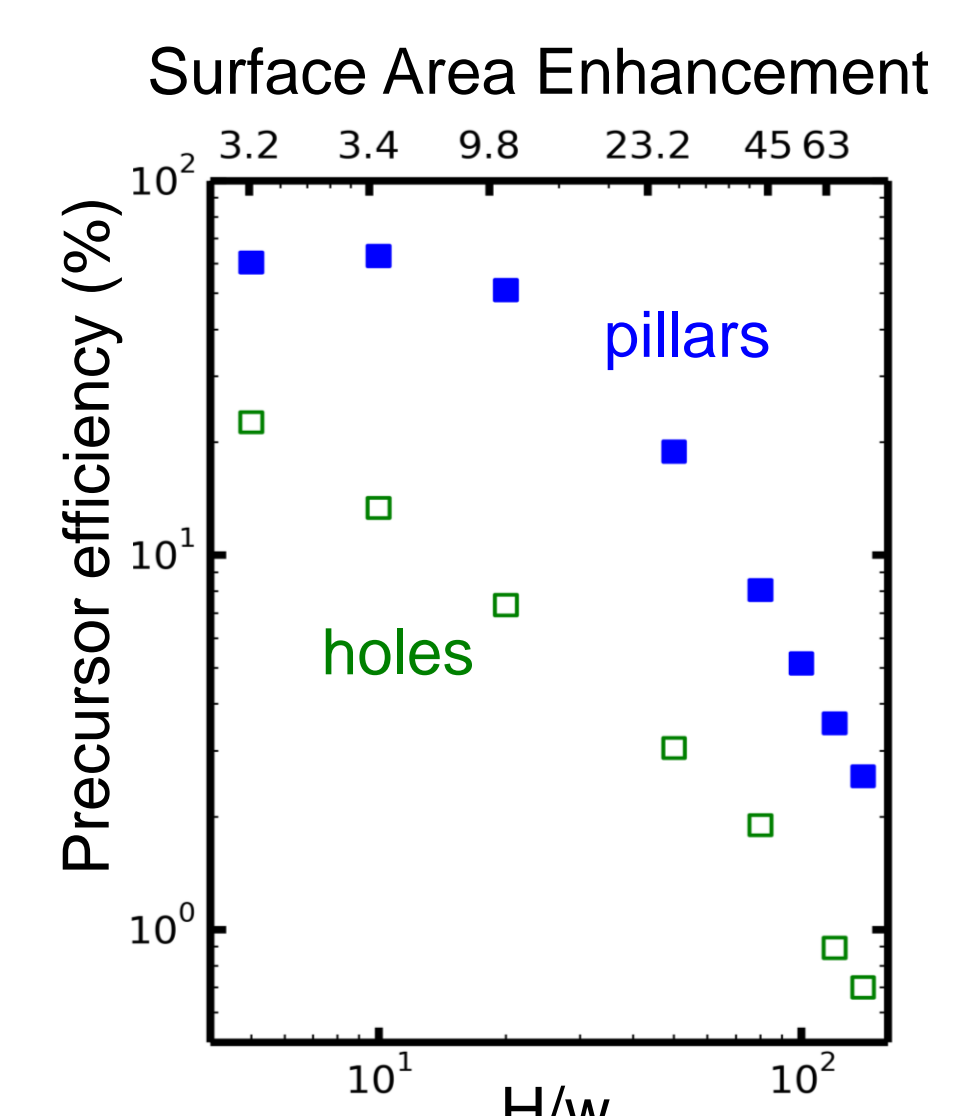
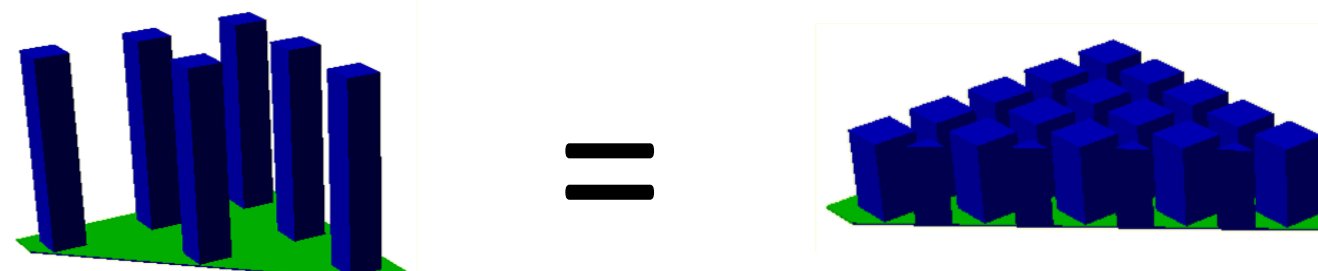
## Results



For a certain SAE factor, e.g. 20, it is easier to coat deep holes with a small spacing than deep holes with a large spacing.



For a certain SAE factor, e.g. 20, the required exposure to cover pillars is independent of the exact geometry (H, w, D).



Less precursor loss in pillar geometry than in hole geometry.

### Conclusion

Lower required exposure, ~precursor cost, for pillar geometries makes them much more suitable for functionalization by ALD.